

ABSTRACT

A metal polishing pad having a functional group which captures a metal ion, a polishing apparatus comprising an apparatus of contacting a polishing subject having a metal surface with the confronting polishing pad according to Claim 1 and applying pressure uniformly between them, an apparatus of rotating or transferring a polishing subject and a polishing pad while maintaining contact between them, and an apparatus of feeding a polish promoting agent for promoting polishing into between a polishing subject and a polishing pad, and a method for polishing a metal by chemical mechanical polishing with the metal polishing apparatus.

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